

What is claimed is:

1. A rectification chip terminal structure, mounting a
rectification chip into a terminal by soldering and rubber
injection and inserting the rectification chip into a pivotal
5 hole on a printed wire board, wherein said terminal
comprising:
a rib ring, surrounding the periphery of said terminal;
a platform extended from the middle section of said
terminal;
10 a first buffer groove formed between said platform and
said rib ring, and having a groove guiding corner; thereby,
when rubber being injected into said terminal, the rubber
going through said first buffer groove to constitute a
fixing action, and forming a plastic surface to prevent
15 water vapor and air from entering after the rubber being
melted and solidified and thus increasing the adhesion
between the injected rubber and said terminal; and said
platform increases the soldering area of said rectification
chip to give a complete solder between said terminal and
20 chip and thus providing the effect for a current of larger
power.
2. The rectification chip terminal structure of claim 1,
wherein said terminal is made integrally, and said terminal
has a plurality of protruded threads on the surface of the
25 periphery of said terminal to facilitate assembling said

terminal into the pivotal hole on a printed wire board, and said first buffer groove has a second buffer groove disposed in said first buffer groove at a position corresponding to the bottom of said terminal.

- 5 3. A rectification chip terminal structure, mounting a rectification chip into a terminal by soldering and rubber injection and inserting the rectification chip into a pivotal hole on a printed wire board, wherein said terminal comprising:
- 10 a rib ring, surrounding the periphery of said terminal;
a platform extended from the middle section of said terminal;
a first buffer groove formed between said platform and said rib ring;
- 15 a protruded ring, extended from the periphery of said platform, and said first buffer groove having a groove guiding corner;
- thereby, when rubber being injected into said terminal, the rubber going through said first buffer groove to constitute
- 20 a fixing action, and forming a plastic surface to prevent water vapor and air from entering after the rubber being melted and solidified and thus increasing the adhesion between the injected rubber and said terminal; and said platform increases the soldering area of said rectification
- 25 chip to give a complete solder between said terminal and

chip and thus providing the effect for a current of larger power.